100 V, 2.0 A, Low V_{CE(sat)} PNP Transistor

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

• This is a Pb-Free Device

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Max	Unit			
Collector-Emitter Voltage	V_{CEO}	-100	Vdc			
Collector-Base Voltage	V_{CB}	-140	Vdc			
Emitter-Base Voltage	V_{EB}	-7.0	Vdc			
Base Current - Continuous	lΒ	1.0	Adc			
Collector Current - Continuous - Peak	lc	2.0 3.0	Adc			
Total Power Dissipation Total P_D @ T_A = 25°C (Note 1) Total P_D @ T_A = 25°C (Note 2)	P_{D}	2.0 0.8	W			
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C			

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient (Note 1) Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	64 155	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	T _L	260	ô

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

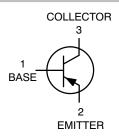
- 1. mounted on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material
- 2. mounted on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material



ON Semiconductor®

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-100 VOLTS, 2.0 AMPS PNP LOW V_{CE(sat)} TRANSISTOR



MARKING DIAGRAM



SOT-223 CASE 318E STYLE 1



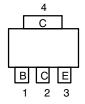
A = Assembly Location

′ = Year

/ = Work Week

1C200 = Specific Device Code ■ Pb-Free Package

PIN ASSIGNMENT



Top View Pinout

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS1C200T1G	SOT-223 (Pb-Free)	1000/ Tape & Reel
NSS1C200T3G	SOT-223 (Pb-Free)	4000/ Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector - Emitter Breakdown Voltage (I _C = -10 mAdc, I _B = 0)	V _{(BR)CEO}	-100			Vdc
Collector - Base Breakdown Voltage (I _C = -0.1 mAdc, I _E = 0)	V _{(BR)CBO}	-140			Vdc
Emitter – Base Breakdown Voltage (I _E = -0.1 mAdc, I _C = 0)	V _{(BR)EBO}	-7.0			Vdc
Collector Cutoff Current (V _{CB} = -140 Vdc, I _E = 0)	I _{CBO}			-100	nAdc
Emitter Cutoff Current (V _{EB} = -6.0 Vdc)	I _{EBO}			-50	nAdc
ON CHARACTERISTICS	•			•	-
DC Current Gain (Note 3) $ (I_C = -10 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -2.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $	h _{FE}	150 120 80 50		360	
Collector – Emitter Saturation Voltage (Note 3) $ \begin{aligned} &(I_C = -0.1 \text{ A, } I_B = -0.010 \text{ A}) \\ &(I_C = -0.5 \text{ A, } I_B = -0.050 \text{ A}) \\ &(I_C = -1.0 \text{ A, } I_B = -0.100 \text{ A}) \\ &(I_C = -2.0 \text{ A, } I_B = -0.200 \text{ A}) \end{aligned} $	V _{CE(sat)}			-0.040 -0.080 -0.125 -0.220	V
Base - Emitter Saturation Voltage (Note 3) (I _C = -1.0 A, I _B = -0.100 A)	V _{BE(sat)}			-0.950	٧
Base - Emitter Turn-on Voltage (Note 3) (I _C = -1.0 A, V _{CE} = -2.0 V)	V _{BE(on)}			-0.850	V
Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, f = 100 MHz)	f⊤		120		MHz
Input Capacitance (V _{EB} = 3.0 V, f = 1.0 MHz)	Cibo		200		pF
Output Capacitance (V _{CB} = 10 V, f = 1.0 MHz)	Cobo		22		pF

^{3.} Pulsed Condition: Pulse Width = 300 msec, Duty Cycle \leq 2%.

TYPICAL CHARACTERISTICS

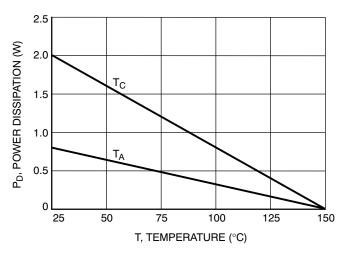


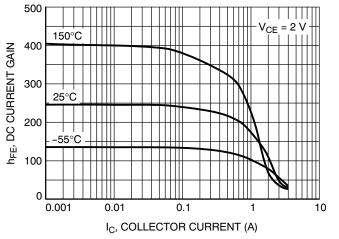
Figure 1. Power Derating

TYPICAL CHARACTERISTICS

500

400

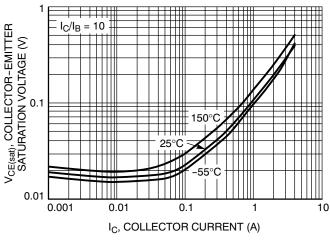
150°C



hFE, DC CURRENT GAIN 300 200 -55°C 100 0 0.001 0.01 0.1 10

Figure 2. DC Current Gain

I_C, COLLECTOR CURRENT (A) Figure 3. DC Current Gain



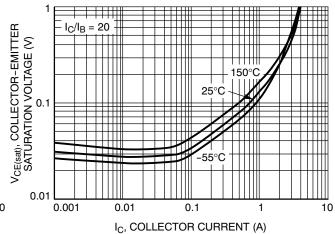
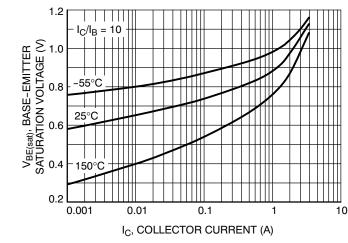


Figure 4. Collector-Emitter Saturation Voltage

Figure 5. Collector-Emitter Saturation Voltage





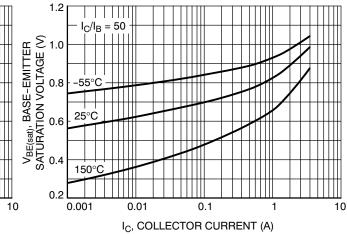
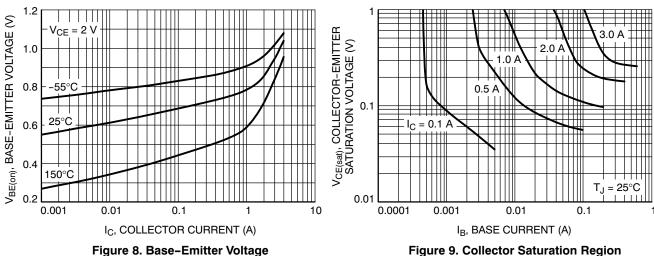


Figure 7. Base-Emitter Saturation Voltage

TYPICAL CHARACTERISTICS



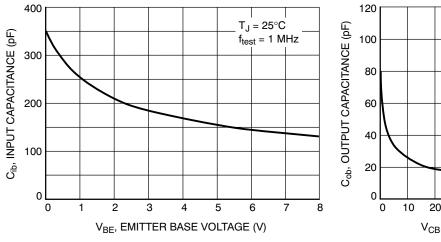


Figure 10. Input Capacitance

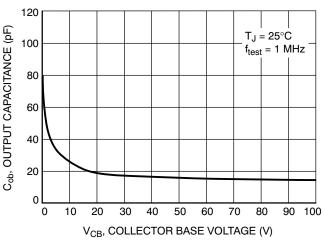


Figure 11. Output Capacitance

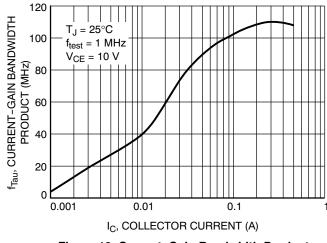


Figure 12. Current-Gain Bandwidth Product

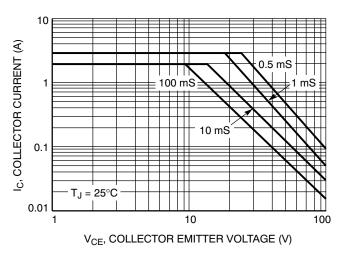
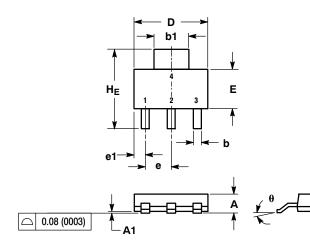


Figure 13. Safe Operating Area

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE L





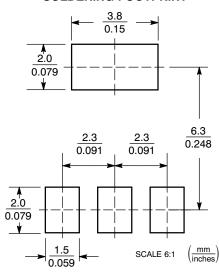
- NOTES: DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 1: PIN 1. BASE

- 2. COLLECTOR 3. EMITTER
- COLLECTOR

SOLDERING FOOTPRINT



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